

## 900V 6A 1.7Ω N-ch Power MOSFET

### Description

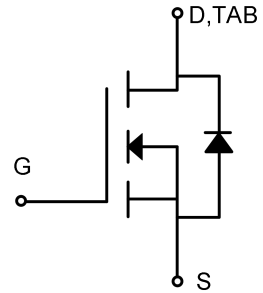
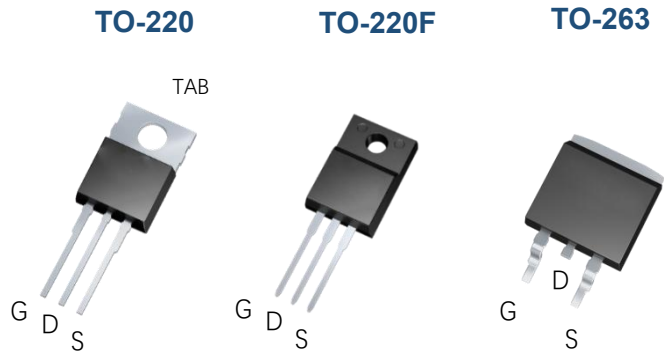
WMOST™ D1 is Wayon's 1<sup>st</sup> generation VDMOS family that is dramatic reduction in on-resistance and ultra-low gate charge for applications requiring high power density and high efficiency. And it is very robust and RoHS compliant.

### Features

- Typ. $R_{DS(on)}=1.7\Omega@V_{GS}=10V$
- 100% avalanche tested
- Pb-free, Halogen free

### Applications

- SMPS
- Charge
- DC-DC



### Absolute Maximum Ratings (T<sub>c</sub>=25°C)

Parameter	Symbol	WMK6N90D1	WML6N90D1	WMM6N90D1	Unit
Drain-source voltage	V <sub>DSS</sub>	900			V
Gate-source voltage	V <sub>GS</sub>	±30			V
Continuous drain current	I <sub>D</sub>	6			A
Pulsed drain current	I <sub>DM</sub>	24			A
Avalanche energy, single pulse	E <sub>AS</sub>	370			mJ
Power dissipation	P <sub>D</sub>	100	50	100	W
Derate above 25°C		0.8	0.4	0.8	W/°C
Operating junction temperature	T <sub>j</sub>	-55~150			°C
Storage temperature	T <sub>stg</sub>	-55~150			°C
Continuous diode forward current	I <sub>S</sub>	6			A
Diode pulse current	I <sub>Spulse</sub>	24			A

### Thermal Characteristic

Thermal resistance, junction-to-case	R <sub>θJC</sub>	1.25	2.5	1.2	°C/W
Thermal resistance, junction-to-ambient	R <sub>θJA</sub>	62.5	62.5	62.5	°C/W

## Electrical Characteristics of MOSFET

				Min.	Typ.	Max.	
Drain-source break down voltage	$BV_{DSS}$	$I_D=250\mu A, V_{GS}=0V$	$T_C=25^\circ C$	900	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$I_D=250\mu A, V_{DS}=V_{GS}$	$T_J=25^\circ C$	3	3.3	5	V
Drain-source leakage current	$I_{DSS}$	$V_{DS}=900V, V_{GS}=0V$	$T_J=25^\circ C$	-	-	1	$\mu A$
		$V_{DS}=720V, V_{GS}=0V$	$T_J=125^\circ C$	-	-	100	$\mu A$
Gate-source leakage current,forward	$I_{GSSF}$	$V_{DS}=0V, V_{GS}=30V$	$T_J=25^\circ C$	-	-	100	nA
Gate-source leakage current,reverse	$I_{GSSR}$	$V_{DS}=0V, V_{GS}=-30V$	$T_J=25^\circ C$	-	-	-100	nA
Drain-source on-state resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=3A$	$T_J=25^\circ C$	-	1.7	2	$\Omega$
Transconductance	$G_{fs}$	$V_{DS}=20V$	$T_J=25^\circ C$	-	7.8	-	S

## Dynamic Characteristics of MOSFET ( $T_C=25^\circ C$ )

				Min.	Typ.	Max.	
Input capacitance	$C_{iss}$	$f=1MHz, V_{DS}=27V, V_{GS}=0V$		-	1390	-	nF
Output capacitance	$C_{oss}$			-	123	-	nF
Reverse transfer capacitance	$C_{rss}$			-	18.7	-	nF
Gate to source charge	$Q_{gs}$	$V_{DD}=450V$		-	18	-	nC
Gate to drain charge	$Q_{gd}$	$I_D=6A$		-	35.2	-	nC
Total gate charge	$Q_g$	$V_{GS}=0$ to 10V		-	86.2	-	nC

## Switching Characteristics of MOSFET ( $T_C=25^\circ C$ )

				Min.	Typ.	Max.	
Turn-on delay time	$t_{d on}$	$V_{DD}=450V, I_D=6A, R_G=25\Omega, V_{GS}=10V$		-	22.8	-	ns
Rise time	$t_r$			-	181	-	ns
Turn-off delay time	$t_{d off}$			-	141	-	ns
Fall time	$t_f$			-	42	-	ns

## Characteristics of Body Diode ( $T_C=25^\circ C$ )

				Min.	Typ.	Max.	
Forward voltage	$V_{SD}$	$I_{SD}=6A, V_{GS}=0V$		-	-	1.4	V
Reverse recovery time	$t_{rr}$	$I_S=6A, V_{GS}=0V, di/dt=100A/\mu s$		-	763	-	ns
Reverse recovery current	$I_{rr}$			-	12.2	-	A
Recovery charge	$Q_{rr}$			-	4.7	-	$\mu C$

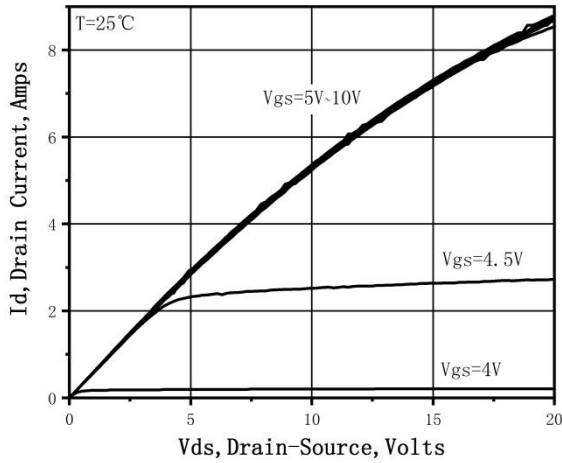


Figure 1. On-Region Characteristics

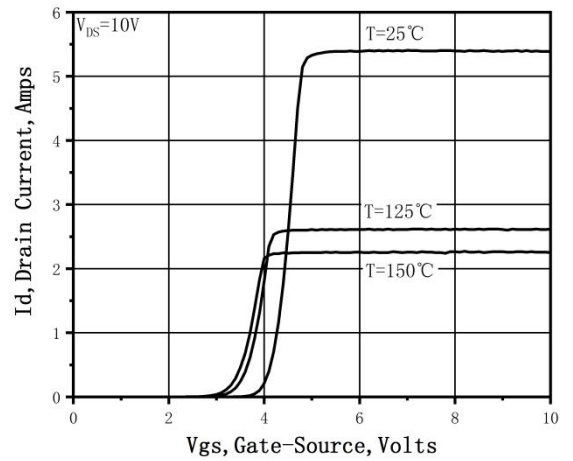


Figure 2. Transfer Characteristics

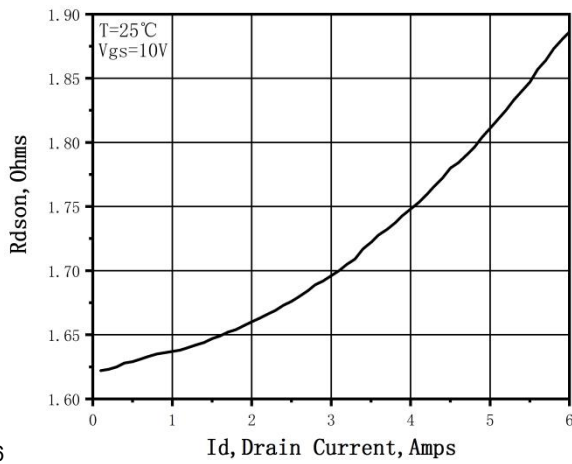


Figure 3. Static Drain-Source On Resistance

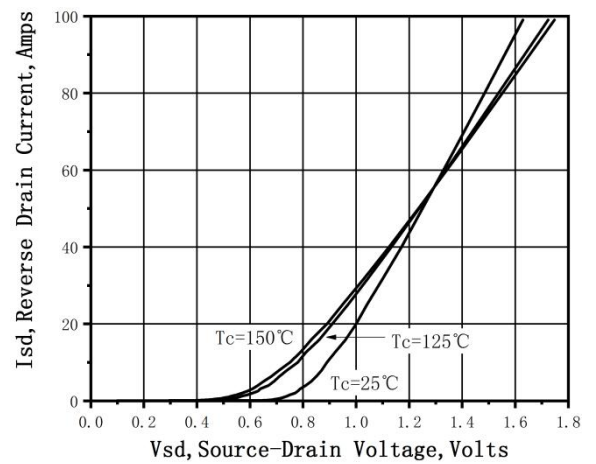


Figure 4. Typical Body Diode Transfer Characteristics

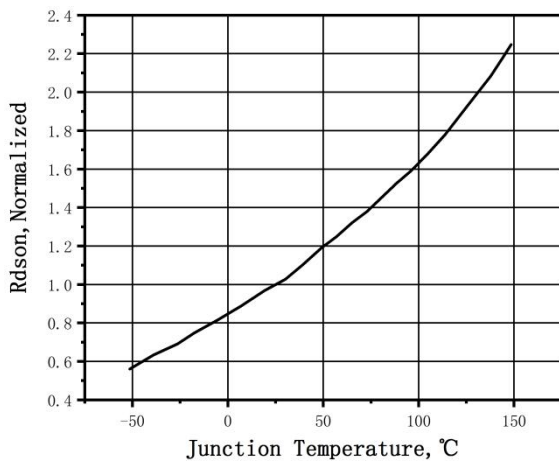


Figure 5. Normalized  $R_{DS(on)}$  vs. Temperature

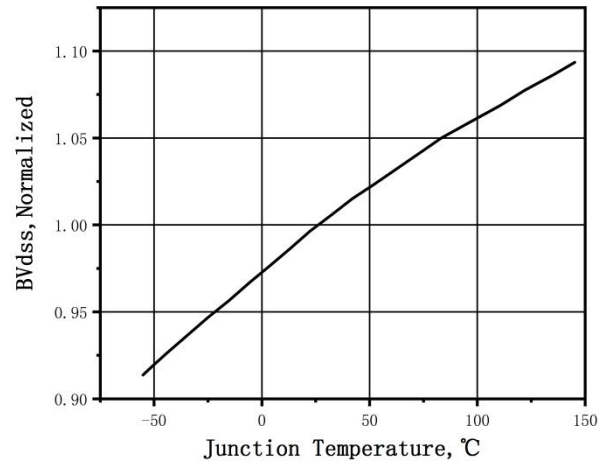


Figure 6. Normalized  $BV_{DSS}$  vs. Temperature

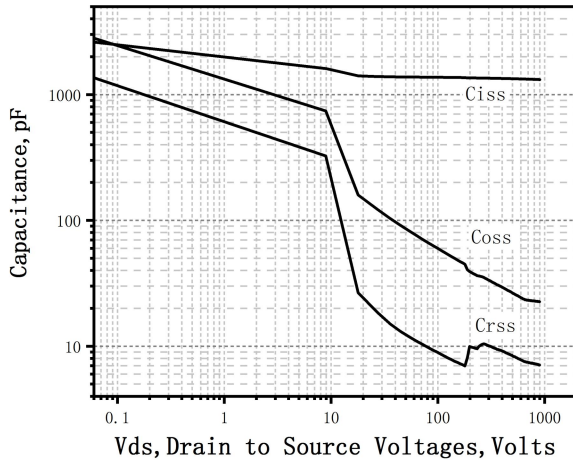


Figure 7. Capacitance Characteristics

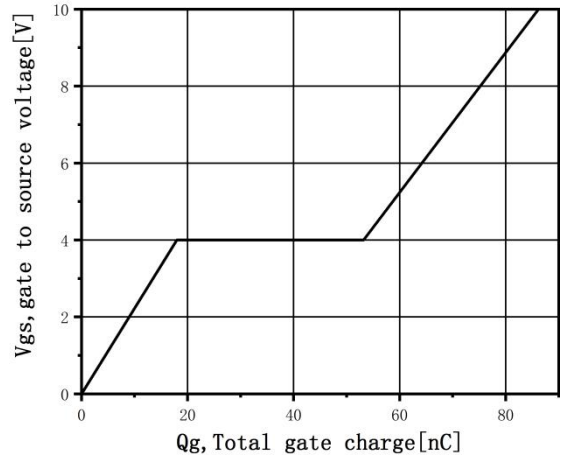


Figure 8. Gate Charge Characteristics

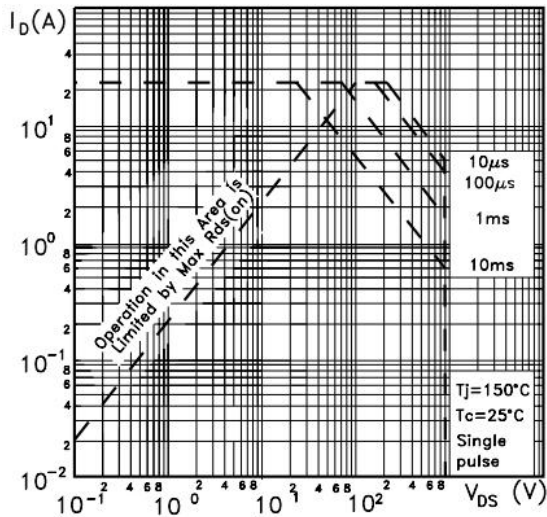


Figure 9. Maximum Safe Operating Area (TO-220/TO-263)

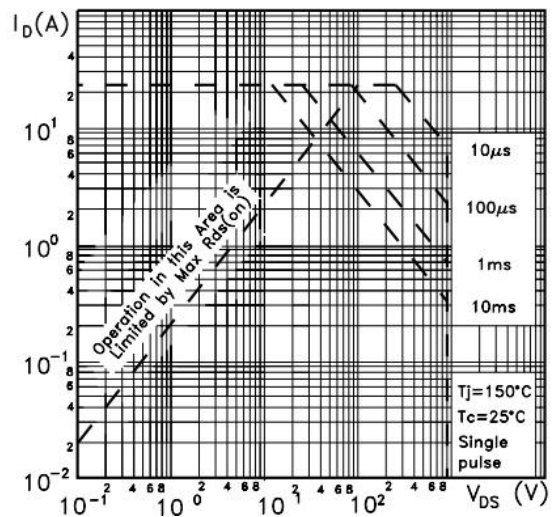


Figure 10. Maximum Safe Operating Area (TO-220F)

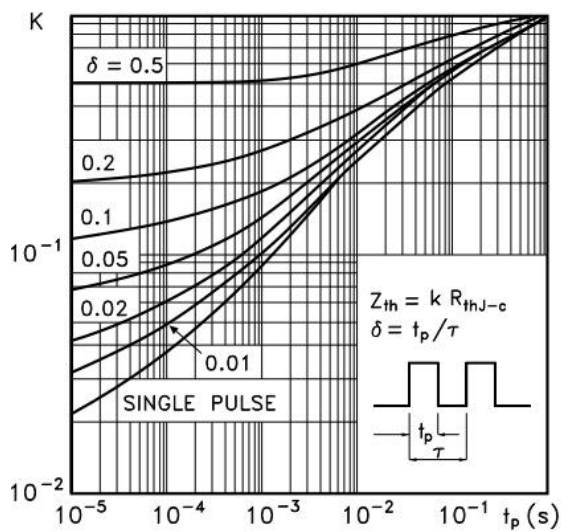


Figure 11. Transient Thermal Response Curve (TO-220/TO-263)

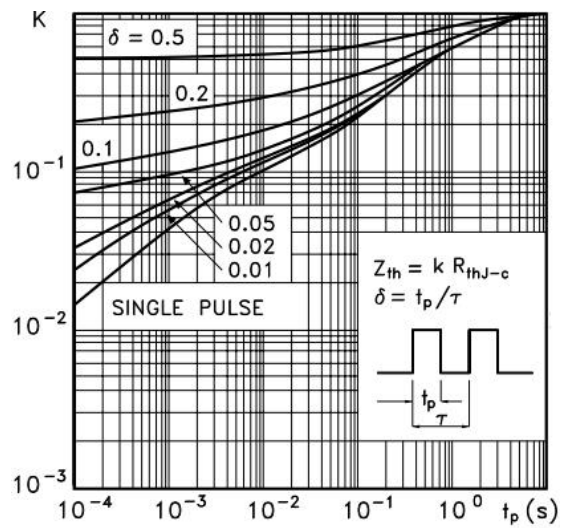
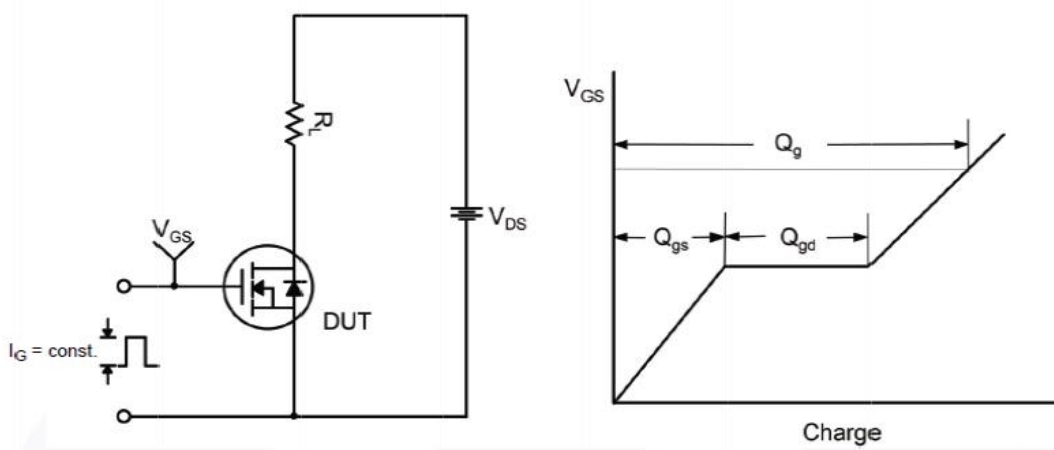
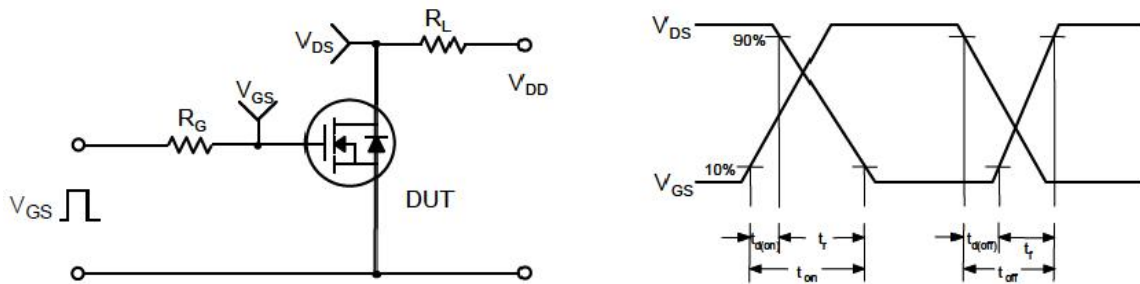


Figure 12. Transient Thermal Response Curve (TO-220F)

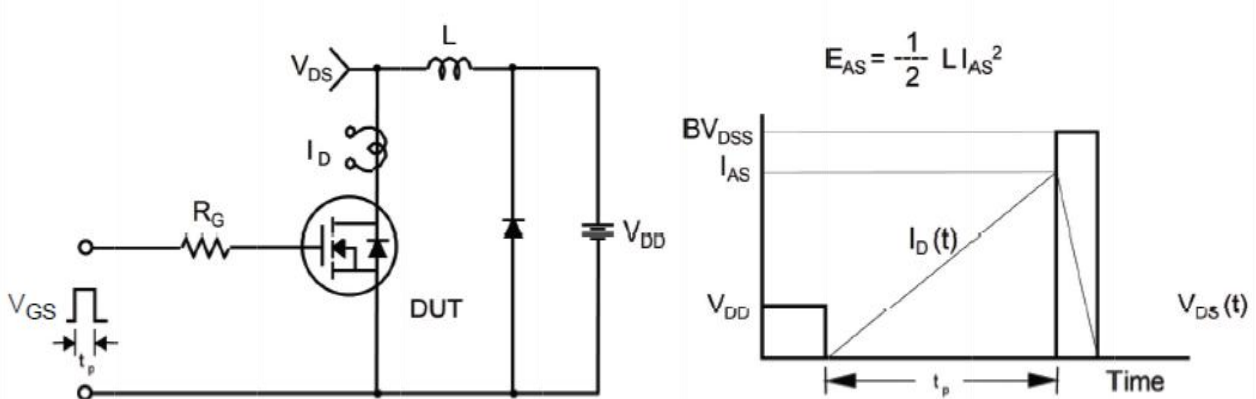
Gate Charge Test Circuit & Waveform



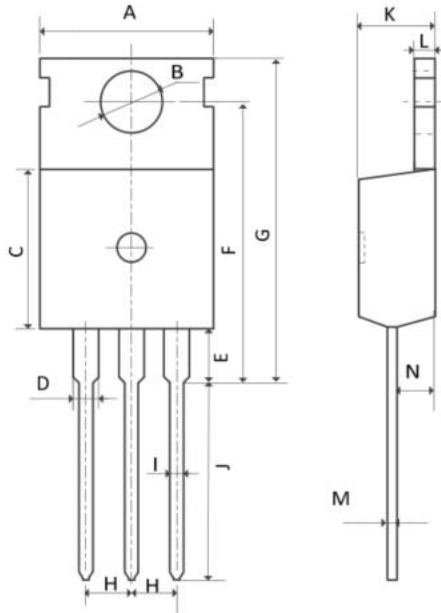
Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



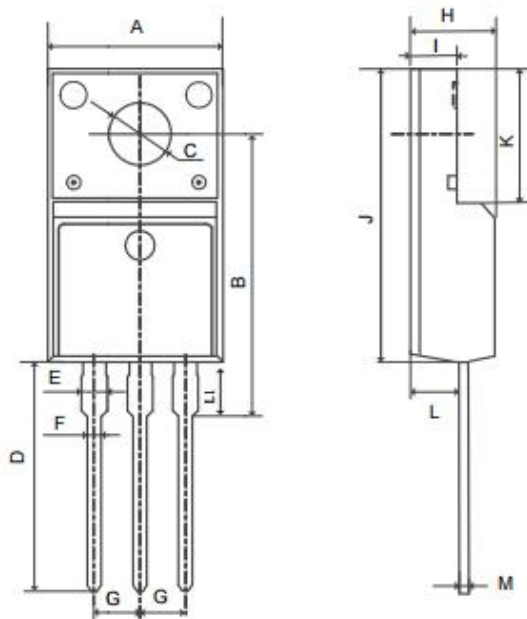
**Mechanical Dimensions for TO-220**



**COMMON DIMENSIONS**

SYMBOL	MM	
	MIN	MAX
A	9.70	10.20
B	3.40	3.80
C	8.90	9.40
D	1.17	1.47
E	2.60	3.40
F	15.10	16.70
G	19.55MAX	
H	2.54REF	
I	0.70	0.95
J	9.35	11.00
K	4.30	4.77
L	1.20	1.45
M	0.40	0.65
N	2.20	2.60

**Mechanical Dimensions for TO-220F**

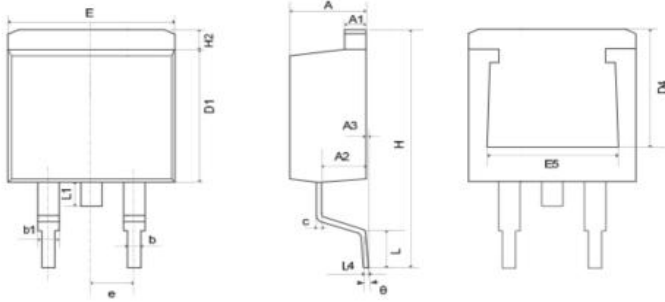


**COMMON DIMENSIONS**

SYMBOL	MM	
	MIN	MAX
A	9.96	10.36
B	15.10	16.10
C	3.03	3.38
D	12.64	13.28
E	1.18	1.58
F	0.70	0.95
G	2.54REF	
H	4.50	4.90
I	2.34	2.74
J	15.57	16.17
K	6.70REF	
L	2.56	2.96
M	0.40	0.65
L1	2.85	3.45

### Mechanical Dimensions for TO-263

COMMON DIMENSIONS

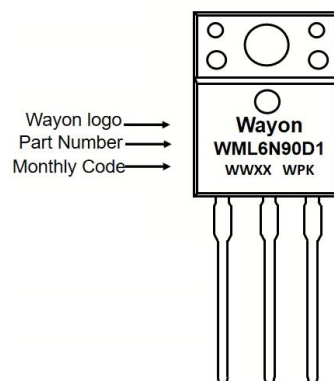


SYMBOL	MM	
	MIN	MAX
A	4.37	4.77
A1	1.22	1.42
A2	2.49	2.89
b	0.70	0.96
b1	1.17	1.47
c	0.30	0.53
D1	8.50	8.90
D4	6.60	—
E	9.86	10.36
E5	7.06	—
e	2.54BSC	
H	14.70	15.50
H2	1.07	1.47
L	2.00	2.60
L1	1.40	1.70
L4	0.25BSC	
θ	0°	9°

### Ordering Information

Part	Package	Marking	Packing method
WMK6N90D1	TO-220	WMK6N90D1	Tube
WML6N90D1	TO-220F	WML6N90D1	Tube
WMM6N90D1	TO-263	WMM6N90D1	Tape and Reel

### Marking Information




## Contact Information

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